

1. ELECTRICAL CHARACTERISTICS:

- 1-1 CURRENT RATING: 1.1 A PER PIN, 30°C RISE ABOVE AMBIENT.
- 1-2 CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL,
50 MILLIOHMS MAX. AFTER TEST.
- 1-3 INSULATION RESISTANCE: 1000 MEGOHMS MIN..
- 1-4 DIELECTRICAL WITHSTAND VOLTAGE: 500 V AC MIN. AT SEA LEVEL.
2. MECHANICAL CHARACTERISTICS:
 - 2-1 CONTACT INSERTION FORCE: 1.15 N MAX. PER CONTACT PAIR.
 - 2-2 CONTACT REMOVAL FORCE: 0.15 N MIN. PER CONTACT PAIR.
 - 2-3 DURABILITY: 50 MATING AND UNMATING CYCLES.
 - 2-4 CONTACT RETENTION FORCE: 4.9 N MIN.
3. ENVIRONMENTAL CHARACTERISTICS:
 - 3-1 OPERATING TEMPERATURE RANGE: -40°C TO +105°C .
4. RECOMMENDED PROCESS: WAVE SOLDER 260°C, 3~5 s
5. HF COMPLIANT.



CONTACT AREA GOLD PLATING:
G= GOLD FLASH
B= 15u" GOLD
C= 30u" GOLD

HOUSING COLOR
B= BLACK
W= WHITE

3	GROUND BAR	SUS304-1/2H		
2	CONTACT	COPPER ALLOY	50u" NICKEL PLATING OVERALL UNDERPLATED. 100u" MATTE TIN PLATING OVER NICKEL AT TAIL. GOLD PLATING ON CONTACT AREA.	
1	HOUSING	THERMOPLASTIC UL 94V-0	MOLDED BLACK OR WHITE	
ITEM	DESCRIPTION	MATERIAL	TREATMENT	
DIM	TOL	DIM	DEG	JOINSOO建舜電子
X	±0.50	X"	±8°	
X.X	±0.35	X.X"	±5°	
X.XX	±0.25	X.XX"	±3°	
X.XXX	±0.15	X.XXX"	±2°	
DESIGN:	ALAN	2022.02.25	FILE:	DRAW NAME:
CHECK:			DRAW NO.	PCIE-X8 Gen4 98P DIP TYPE CONN
APPROVED			P/N: 121P-C8E*-J7*T	
			UNIT: mm	SCALE: 2:1
			REV: 04	SHEET: 1/2
			MODEL:	-

JOINS00建舜電子

FILE:

DRAW NAME:

DRAW NO.

PCIE-X8 Gen4

P/N: 121P-C8E*-J7*T

98P DIP TYPE CONN

UNIT: *mm*

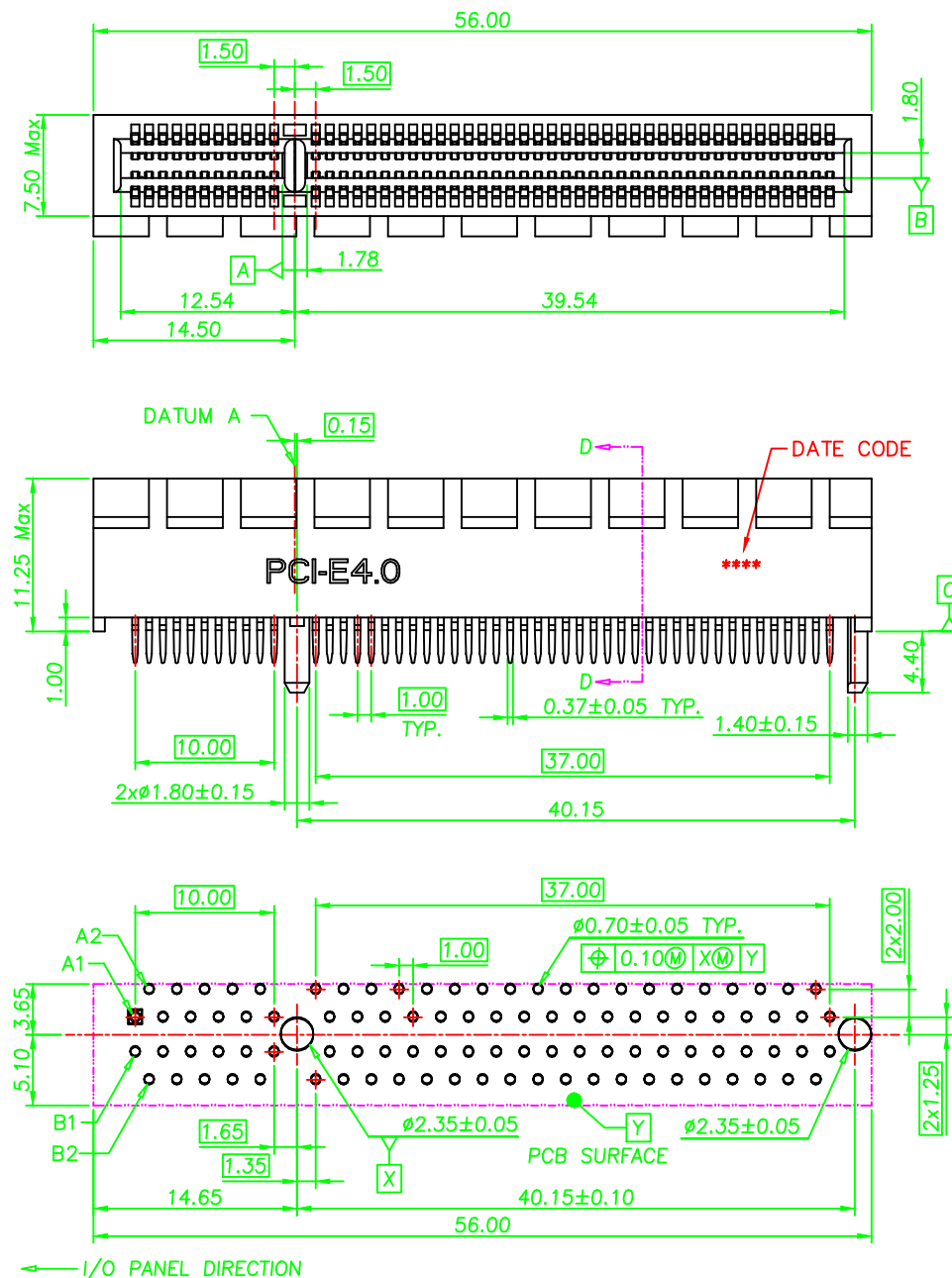
SCALE: 2:1

MODEL:

REV: 04

SHEET: 1/2

100



RECOMMENDED PCB LAYOUT

